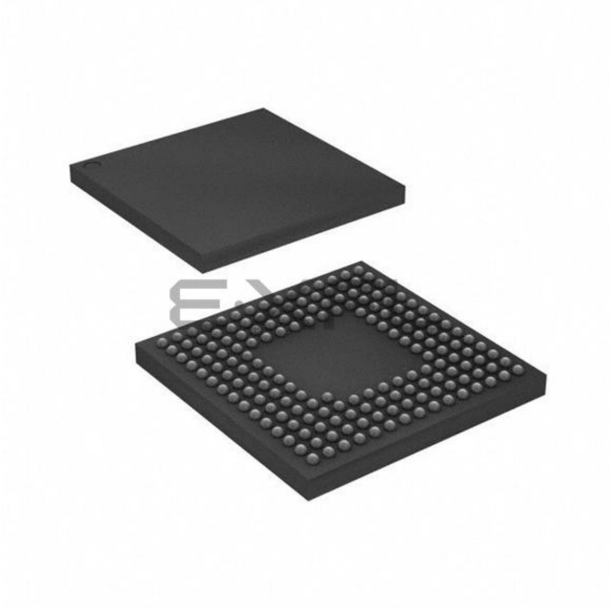
Renesas Electronics America Inc - R5F5631BCDLC#U0 Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	CANbus, EBI/EMI, I²C, LINbus, SCI, SPI, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	133
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	32K x 8
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 8x10b, 21x12b; D/A 2x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	177-TFLGA
Supplier Device Package	177-TFLGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f5631bcdlc-u0

Table 1.4 Pin Functions (2/6)

Classifications	Pin Name	I/O	Description
Bus control	RD#	Output	Strobe signal which indicates that reading from the external bus interface space is in progress.
	WR#	Output	Strobe signal which indicates that writing to the external bus interface space is in progress, in 1-write strobe mode.
	WR0# to WR3#	Output	Strobe signals which indicate that either group of data bus pins (D7 to D0, D15 to D8, D23 to D16, and D31 to D24) is valid in writing to the external bus interface space, in byte strobe mode.
	BC0# to BC3#	Output	Strobe signals which indicate that either group of data bus pins (D7 to D0, D15 to D8, D23 to D16, and D31 to D24) is valid in access to the external bus interface space, in 1-write strobe mode.
	ALE	Output	Address latch signal when address/data multiplexed bus is selected.
	CKE	Output	Output pin for SDRAM clock enable signals.
	SDCS#	Output	Output pin for SDRAM chip select signals.
	RAS#	Output	Output pin for SDRAM row address strobe signals.
	CAS#	Output	Output pin for SDRAM column address strobe signals.
	WE#	Output	Output pin for SDRAM write enable signals.
	DQM0 to DQM3	Output	Output pins for SDRAM I/O data mask enable signals.
	CS0# to CS7#	Output	Select signals for CS area.
	WAIT#	Input	Input pins for wait request signals in access to the external space.
EXDMA controller	EDREQ0, EDREQ1		Input pins for external DMA transfer requests.
	EDACK0, EDACK1		Output pins for single address transfer acknowledge signals.
Interrupt	NMI	Input	Non-maskable interrupt request signal.
	IRQ0 to IRQ15	Input	Maskable interrupt request signals.
Multi-function timer pulse unit 2	MTIOC0A, MTIOC0B MTIOC0C, MTIOC0D	I/O	The TGRA0 to TGRD0 input capture input/output compare output/PWM output pins.
	MTIOC1A, MTIOC1B	I/O	The TGRA1 and TGRB1 input capture input/output compare output/PWM output pins.
	MTIOC2A, MTIOC2B	I/O	The TGRA2 and TGRB2 input capture input/output compare output/PWM output pins.
	MTIOC3A, MTIOC3B MTIOC3C, MTIOC3D	I/O	The TGRA3 to TGRD3 input capture input/output compare output/PWM output pins.
	MTIOC4A, MTIOC4B MTIOC4C, MTIOC4D	I/O	The TGRA4 to TGRD4 input capture input/output compare output/PWM output pins.
	MTIC5U, MTIC5V MTIC5W	Input	The TGRU5, TGRV5, and TGRW5 input capture input/dead time compensation input pins.
	MTCLKA, MTCLKB MTCLKC, MTCLKD	Input	Input pins for external clock signals.
Port output enable 2	POE0# to POE3# POE8#	Input	Input pins for request signals to place the MTU large-current pins in the high impedance state.

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	
15	PE2	PE3	P70	P65	P67	VSS	VCC	PG7	PA6	PB0	P72	PB4	VSS	VCC	PC1	15
14	PE1	PE0	VSS	PE7	PG3	PA0	PA1	PA2	PA7	VCC	PB1	PB5	P73	P75	P74	14
13	P63	P64	PE4	VCC	PG2	PG4	PG6	PA3	VSS	P71	PB3	PB7	PC0	PC2	P76	13
12	P60	VSS	P62	PE5	PE6	P66	PG5	PA4	PA5	PB2	PB6	P77	PC3	PC4	P80	12
11	PD6	PG1	VCC	P61								P81	P82	PC6	VCC	11
10	P97	PD4	PG0	PD7								PC5	PC7	P83	VSS	10
9	VCC	P96	PD3	PD5								P50	P51	P52	P84	9
8	P94	PD1	PD2	VSS								P53	VCC_USB	USB1_DP	USB1_DM	8
7	VSS	P92	PD0	P95								P54	P55	VSS_USB	USB0_DP	7
6	VCC	P91	P90	P93								P56	P57	VCC_USB	USB0_DM	6
5	P46	P47	P45	P44								P13	P12	P10	P11	5
4	P42	P41	P43	P00	VSS	BSCANP	PF4	P35	PF3	PF1	P25	P86	P15	P14	P85	4
3	VREFL0	P40	VREFH0	P03	PF5	PJ3	MD/FINED	RES#	P34	PF2	PF0	P24	P22	P87	P16	3
2	AVCC0	P07	VREFH	P02	EMLE	VCL	XCOUT	VSS	VCC	P32	P30	P26	P23	P17	P20	2
1	AVSS0	P05	VREFL	P01	PJ5	VBATT	XCIN	XTAL	EXTAL	P33	P31	P27	VCC	VSS	P21	1
	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	

RX63N Group
RX631 Group
PTBG0176GA-A
(176-pin LFBGA)
(Top perspective view)

Note: This figure indicates the power supply pins and I/O port pins. For the pin configuration, see Table 1.5, List of Pin and Pin Functions (177-Pin TFLGA, 176-Pin LFBGA).

Figure 1.4 Pin Assignment (176-Pin LFBGA)

RX63N Group, RX631 Group
PTLG0100JA-A (100-pin TFLGA)
(Top view)

	A	B	C	D	E	F	G	H	J	K	
10	PE2	PE3	PE4	PA0	PA3	VSS	VCC	PB7	PC1	PC2	10
9	PE1	PD7	PE5	PA1	PA5	PA7	PB1	PB6	PC0	PC3	9
8	PE0	PD6	PD5	PE7	PA4	PB0	PB4	PC6	PC4	PC5	8
7	PD4	PD3	PD2	PE6	PA6	PB2	PB5	PC7	P50	P51	7
6	PD0	PD1	P47	P46	PA2	PB3	P52	P54	VCC_ USB	USB0_ DP	6
5	P43	P44	P42	P45	P41	P12	P53	P55	VSS_ USB	USB0_ DM	5
4	VREFL0	P40	VREFH0	VBATT	P34	P32	P27	P15	P13	P14	4
3	P07	AVCC0	PJ3	MD/ FINED	RES#	P35	P30	P16	P17	P20	3
2	VREFH	AVSS0	VREFL	XCOUT	VSS	VCC	P31	P25	P21	P22	2
1	P05	EMLE	VCL	XCIN	XTAL	EXTAL	P33	P26	P24	P23	1
	A	B	C	D	E	F	G	H	J	K	

Note: This figure indicates the power supply pins and I/O port pins. For the pin configuration, see Table 1.10, List of Pins and Pin Functions (100-Pin LQFP).

Figure 1.8 Pin Assignment (100-Pin TFLGA)

Table 1.5 List of Pin and Pin Functions (177-Pin TFLGA, 176-Pin LFBGA) (3/5)

Pin Number 177-Pin TFLGA 176-Pin LFBGA	Power Supply Clock System Control	I/O Port	Bus EXDMAC SDRAMC	Timer (MTU, TPU, TMR, PPG, RTC, POE)	Communications (ETHERC, SCIc, SCId, RSPI, RIIC, CAN, IEB, USB, and PDC)	Interrupt	S12AD, AD, DA
H3	RES#						
H4		P35				NMI	
H12		PA4	A4	MTIC5U/MTCLKA/TIOCA1/TMRI0/PO20	ET_MDC/TXD5/SMOSI5/SSDA5/SSLA0	IRQ5-DS	
H13		PA3	A3	MTIOC0D/MTCLKD/TIOCD0/TCLKB/PO19	ET_MDIO/RXD5/SMISO5/SSCL5	IRQ6-DS	
H14		PA2	A2	PO18	RXD5/SMISO5/SSCL5/SSLA3		
H15	TRDATA3	PG7	D31				
J1	EXTAL	P36					
J2	VCC						
J3		P34		MTIOC0A/TMCI3/PO12/POE2#	SCK6/SCK0/USB0_DPRPD	IRQ4	
J4	TMS	PF3					
J12		PA5	A5	TIOCB1/PO21	ET_LINKSTA/RSPCKA		
J13	VSS						
J14		PA7	A7	TIOCB2/PO23	ET_WOL/MISOA		
J15		PA6	A6	MTIC5V/MTCLKB/TIOCA2/TMCI3/PO22/POE2#	ET_EXOUT/CTS5#/RTS5#/SS5#/MOSIA		
K1		P33		MTIOC0D/TIOCD0/TMRI3/PO11/POE3#	RXD6/RXD0/SMISO6/SMISO0/SSCL6/SSCL0/CRX0/PCKO	IRQ3-DS	
K2		P32		MTIOC0C/TIOCC0/TMO3/PO10/RTCOUT/RTCIC2	TXD6/TXD0/SMOSI6/SMOSI0/SSDA6/SSDA0/CTX0/USB0_VBUSEN/VSYNC	IRQ2-DS	
K3	TDI	PF2			RXD1/SMISO1/SSCL1		
K4	TCK/FINEC	PF1			SCK1		
K12		PB2	A10	TIOCC3/TCLKC/PO26	ET_RX_CLK/REF50CK/CTS4#/RTS4#/CTS6#/RTS6#/SS4#/SS6#		
K13		P71	CS1#		ET_MDIO		
K14	VCC						
K15		PB0	A8	MTIC5W/TIOCA3/PO24	ET_ERXD1/RMII_RXD1/RXD4/RXD6/SMISO4/SMISO6/SSCL4/SSCL6/RSPCKA	IRQ12	
L1		P31		MTIOC4D/TMCI2/PO9/RTCIC1	CTS1#/RTS1#/SS1#/SSLB0/USB0_DPUPE	IRQ1-DS	
L2		P30		MTIOC4B/TMRI3/PO8/RTCIC0/POE8#	RXD1/SMISO1/SSCL1/MISOB/USB0_DRPD	IRQ0-DS	
L3	TDO	PF0			TXD1/SMOSI1/SSDA1		
L4		P25	CS5#/EDACK1	MTIOC4C/MTCLKB/TIOCA4/PO5	RXD3/SMISO3/SSCL3/USB0_DPRPD/HSYNC		ADTRG0#
L12		PB6	A14	MTIOC3D/TIOCA5/PO30	ET_ETXD1/RMII_TXD1/RXD9/SMISO9/SSCL9		
L13		PB3	A11	MTIOC0A/MTIOC4A/TIOCD3/TCLKD/TMO0/PO27/POE3#	ET_RX_ER/RMII_RX_ER/SCK4/SCK6		
L14		PB1	A9	MTIOC0C/MTIOC4C/TIOCB3/TMCI0/PO25	ET_ERXD0/RMII_RXD0/TXD4/TXD6/SMOSI4/SMOSI6/SSDA4/SSDA6	IRQ4-DS	
L15		P72	CS2#		ET_MDC		
M1		P27	CS7#	MTIOC2B/TMCI3/PO7	SCK1/RSPCKB		

Note 3. Enabled only for the ROM capacity: 2 Mbytes/1.5 Mbytes

Table 1.6 List of Pin and Pin Functions (176-Pin LQFP) (5/5)

Pin Number 176-Pin LQFP	Power Supply Clock System Control	I/O Port	Bus EXDMAC SDRAMC	Timer (MTU, TPU, TMR, PPG, RTC, POE)	Communications (ETHERC, SCIc, SCId, RSPI, RIIC, CAN, IEB, USB, and PDC)	Interrupt	S12AD, AD, DA
136		P64	CS4#/WE#				
137		P63	CS3#/CAS#				
138		P62	CS2#/RAS#				
139		P61	CS1#/SDCS#				
140	VSS						
141		P60	CS0#				
142	VCC						
143		PD7	D7[A7/D7]	MTIC5U/POE0#	SSLC3	IRQ7	AN7
144		PG1	D25				
145		PD6	D6[A6/D6]	MTIC5V/POE1#	SSLC2	IRQ6	AN6
146		PG0	D24				
147		PD5	D5[A5/D5]	MTIC5W/POE2#	SSLC1	IRQ5	AN013
148		PD4	D4[A4/D4]	POE3#	SSLC0	IRQ4	AN012
149		P97	A23/D23				
150		PD3	D3[A3/D3]	TIOCB8/TCLKH/POE8#	RSPCKC	IRQ3	AN011
151	VSS						
152		P96	A22/D22				
153	VCC						
154		PD2	D2[A2/D2]	MTIOC4D/TIOCA8	MISOC/CRX0	IRQ2	AN010
155		P95	A21/D21				
156		PD1	D1[A1/D1]	MTIOC4B/TIOCB7/ TCLKG	MOSIC/CTX0	IRQ1	AN009
157		P94	A20/D20				
158		PD0	D0[A0/D0]	TIOCA7		IRQ0	AN008
159		P93	A19/D19		CTS7#/RTS7#/SS7#		AN017
160		P92	A18/D18		RXD7/SMISO7/SSCL7		AN016
161		P91	A17/D17		SCK7		AN015
162	VSS						
163		P90	A16/D16		TXD7/SMOSI7/SSDA7		AN014
164	VCC						
165		P47				IRQ15-DS	AN007
166		P46				IRQ14-DS	AN006
167		P45				IRQ13-DS	AN005
168		P44				IRQ12-DS	AN004
169		P43				IRQ11-DS	AN003
170		P42				IRQ10-DS	AN002
171		P41				IRQ9-DS	AN001
172	VREFL0						
173		P40				IRQ8-DS	AN000
174	VREFH0						
175	AVCC0						
176		P07				IRQ15	ADTRG0#

Note 1. The BCLK function is multiplexed with the I/O port function for pin P53, so the port function is not available if the external bus is enabled.

Note 2. Enabled only for the ROM capacity: 2 Mbytes/1.5 Mbytes

Table 1.8 List of Pins and Pin Functions (144-Pin LQFP) (3/5)

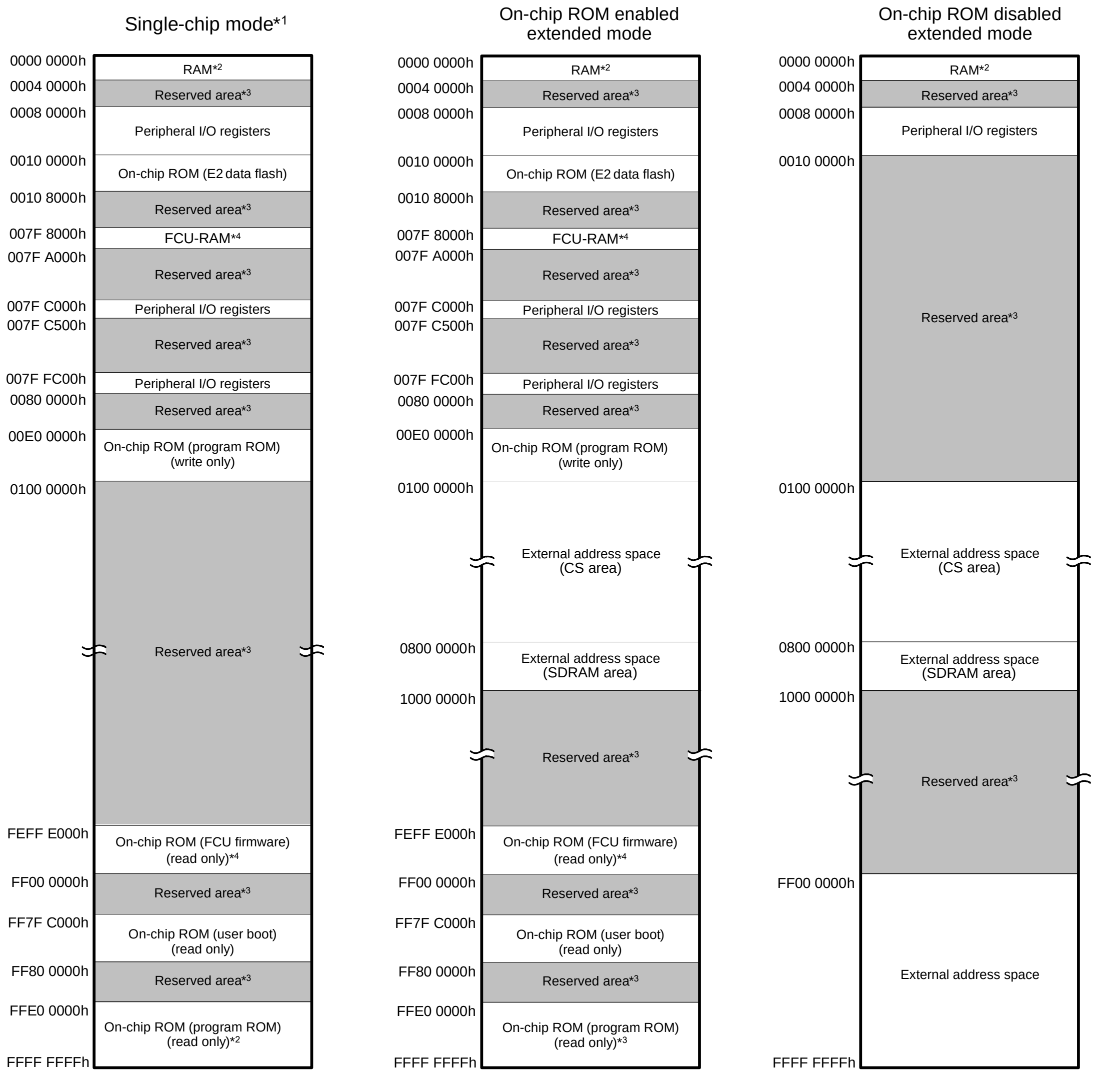
Pin No.				Timers	Communications		
144-pin LQFP	Power Supply Clock System Control	I/O Port	Bus EXDMAC SDRAMC	(MTU, TPU, TMR, PPG, RTC, POE)	(ETHERC, SCIc, SCId, RSPI, RIIC, CAN, IEB, USB, and PDC)	Interrupt	S12AD AD DA
64	TRDATA1	P81	EDACK0	MTIOC3D/PO27	RXD10/SMISO10/SSCL10/ET_ETXD0/RMII_TXD0		
65	TRDATA0	P80	EDREQ0	MTIOC3B/PO26	SCK10/ET_TX_EN/RMII_TXD_EN		
66		PC4	A20/CS3#	MTIOC3D/MTCLKC/TIOCC6/TCLKE/TMCI1/PO25/POE0#	SCK5/CTS8#/RTS8#/SS8#/SSLA0/ET_TX_CLK		
67		PC3	A19	MTIOC4D/TCLKB/PO24	TXD5/SMOSI5/SSDA5/IETXD/ET_TX_ER		
68		P77	CS7#	PO23	TXD11/SMOSI11/SSDA11/ET_RX_ER/RMII_RX_ER		
69		P76	CS6#	PO22	RXD11/SMISO11/SSCL11/ET_RX_CLK/REF50CK		
70		PC2	A18	MTIOC4B/TCLKA/PO21	RXD5/SMISO5/SSCL5/SSLA3/IERXD/ET_RX_DV		
71		P75	CS5#	PO20	SCK11/ET_ERXD0/RMII_RXD0		
72		P74	CS4#	PO19	CTS11#/RTS11#/SS11#/ET_ERXD1/RMII_RXD1		
73		PC1	A17	MTIOC3A/TCLKD/PO18	SCK5/SSLA2/SDA3/ET_ERXD2	IRQ12	
74	VCC						
75		PC0	A16	MTIOC3C/TCLKC/PO17	CTS5#/RTS5#/SS5#/SSLA1/SCL3/ET_ERXD3	IRQ14	
76	VSS						
77		P73	CS3#	PO16	ET_WOL		
78		PB7	A15	MTIOC3B/TIOCB5/PO31	TXD9/SMOSI9/SSDA9/ET_CRS/RMII_CRS_DV		
79		PB6	A14	MTIOC3D/TIOCA5/PO30	RXD9/SMISO9/SSCL9/ET_ETXD1/RMII_TXD1		
80		PB5	A13	MTIOC2A/MTIOC1B/TIOCB4/TMRI1/PO29/POE1#	SCK9/ET_ETXD0/RMII_TXD0		
81		PB4	A12	TIOCA4/PO28	CTS9#/RTS9#/SS9#/ET_TX_EN/RMII_TXD_EN		
82		PB3	A11	MTIOC0A/MTIOC4A/TIOCD3/TCLKD/TMO0/PO27/POE3#	SCK4/SCK6/ET_RX_ER/RMII_RX_ER		
83		PB2	A10	TIOCC3/TCLKC/PO26	CTS4#/RTS4#/CTS6#/RTS6#/SS4#/SS6#/ET_RX_CLK/REF50CK		
84		PB1	A9	MTIOC0C/MTIOC4C/TIOCB3/TMCI0/PO25	TXD4/TXD6/SMOSI4/SMOSI6/SSDA4/SSDA6/ET_ERXD0/RMII_RXD0	IRQ4-DS	
85		P72	CS2#		ET_MDC		
86		P71	CS1#		ET_MDIO		
87		PB0	A8	MTIC5W/TIOCA3/PO24	RXD4/RXD6/SMISO4/SMISO6/SSCL4/SSCL6/RSPCKA/T_ERXD1/RMII_RXD1	IRQ12	
88		PA7	A7	TIOCB2/PO23	MISOA/ET_WOL		

Table 1.12 List of Pins and Pin Functions (64-Pin LQFP) (2/3)

Pin Number 64-Pin LQFP	Power Supply Clock System Control	I/O Port	Timer (MTU2a, TPUa, TMR, PPG, RTCa, POE2a)	Timer Communications (SCIc, SCId, RSPI, RIIC, CAN, IEB, USB)	Interrupt	S12ADa, DAa
32		PC2	MTIOC4B/TCLKA/PO21	RXD5/SMISO5/SSCL5/SSLA3/IERXD		
33		PB7/PC1	MTIOC3B/TIOCB5/PO31	TXD9/SMOSI9/SSDA9		
34		PB6/PC0	MTIOC3D/TIOCA5/PO30	RXD9/SMISO9/SSCL9		
35		PB5	MTIOC2A/MTIOC1B/TIOCB4/TMRI1/PO29/POE1#	SCK9		
36		PB3	MTIOC0A/MTIOC4A/TIOCD3/TCLKD/TMO0/PO27/POE3#	SCK6		
37		PB1	MTIOC0C/MTIOC4C/TIOCB3/TMCI0/PO25	TXD6/SMOSI6/SSDA6	IRQ4-DS	
38	VCC					
39		PB0	MTIC5W/TIOCA3/PO24	RXD6/SMISO6/SSCL6/RSPCKA	IRQ12	
40	VSS					
41		PA6	MTIC5V/MTCLKB/TIOCA2/TMCI3/PO22/POE2#	CTS5#/RTS5#/SS5#/MOSIA		
42		PA4	MTIC5U/MTCLKA/TIOCA1/TMRI0/PO20	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5-DS	
43		PA3	MTIOC0D/MTCLKD/TIOCD0/TCLKB/PO19	RXD5/SMISO5/SSCL5	IRQ6-DS	
44		PA1	MTIOC0B/MTCLKC/TIOCB0/PO17	SCK5/SSLA2/SCL2	IRQ11	
45		PA0	MTIOC4A/TIOCA0/PO16	SSLA1		
46		PE5	MTIOC4C/MTIOC2B	RSPCKB	IRQ5	AN013
47		PE4	MTIOC4D/MTIOC1A/PO28	SSLB0		AN012
48		PE3	MTIOC4B/PO26/POE8#	CTS12#/RTS12#/SS12#/MISOB		AN011
49		PE2	MTIOC4A/PO23	RXD12/SMISO12/SSCL12/RXDX12/SSLB3/MOSIB	IRQ7-DS	AN010
50		PE1	MTIOC4C/PO18	TXD12/SMOSI12/SSDA12/TXDX12/SIOX12/SSLB2/RSPCKB		AN009
51		PE0		SCK12/SSLB1		AN008
52	VREFL					
53		P46			IRQ14-DS	AN006
54	VREFH					
55		P44			IRQ12-DS	AN004
56		P43			IRQ11-DS	AN003
57		P42			IRQ10-DS	AN002
58		P41			IRQ9-DS	AN001
59	VREFL0					
60		P40			IRQ8-DS	AN000

Table 1.12 List of Pins and Pin Functions (64-Pin LQFP) (3/3)

Pin Number 64-Pin LQFP	Power Supply Clock System Control	I/O Port	Timer (MTU2a, TPUa, TMR, PPG, RTCa, POE2a)	Timer Communications (SCIc, SCId, RSPI, RIIC, CAN, IEB, USB)	Interrupt	S12ADa, DAa
61	VREFH0					
62	AVCC0					
63		P05			IRQ13	DA1
64	AVSS0					



Note 1. The address space in boot mode and user boot mode/USB boot mode is the same as the address space in single-chip mode.
Note 2. The capacity of ROM/RAM differs depending on the products.

ROM (byt)			RAM (byt)	
Capacity	**Address (for reading only)**	**Address (for programming only)**	**Capacity**	**Address**
2 M	FFE0 0000h to FFFF FFFFh	00E0 0000h to 00FF FFFFh	256 K	0000 0000h to 0003 FFFFh
			192 K	0000 0000h to 0002 FFFFh
			128 K	0000 0000h to 0001 FFFFh
1.5 M	FFE8 0000h to FFFF FFFFh	00E8 0000h to 00FF FFFFh	256 K	0000 0000h to 0003 FFFFh
			192 K	0000 0000h to 0002 FFFFh
			128 K	0000 0000h to 0001 FFFFh
1 M	FFF0 0000h to FFFF FFFFh	00F0 0000h to 00FF FFFFh	256 K	0000 0000h to 0003 FFFFh
			192 K	0000 0000h to 0002 FFFFh
			128 K	0000 0000h to 0001 FFFFh
768 K	FFF4 0000h to FFFF FFFFh	00F4 0000h to 00FF FFFFh		
512K	FFF8 0000h to FFFF FFFFh	00F8 0000h to 00FF FFFFh		
384K	FFFA 0000h to FFFF FFFFh	00FA 0000h to 00FF FFFFh		
256K	FFFC 0000h to FFFF FFFFh	00FC 0000h to 00FF FFFFh		
512K	FFF8 0000h to FFFF FFFFh	00F8 0000h to 00FF FFFFh	64K	0000 0000h to 0000 FFFFh
384K	FFFA 0000h to FFFF FFFFh	00FA 0000h to 00FF FFFFh		
256K	FFFC 0000h to FFFF FFFFh	00FC 0000h to 00FF FFFFh		

Note:See Table 1.3, List of Products, for the product type name.

Note 3. Reserved areas should not be accessed.
Note 4. For details on the FCU, see section 47, Flash Memory in the User's manual: Hardware.

Figure 3.1 Memory Map in Each Operating Mode

Table 4.1 List of I/O Registers (Address Order) (24/50)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States		Related Function
						ICLK≥PCLK	ICLK<PCLK	
0008 9034h	S12AD	A/D data register 10	ADDR10	16	16	2, 3 PCLKB	2 ICLK	S12ADa
0008 9036h	S12AD	A/D data register 11	ADDR11	16	16	2, 3 PCLKB	2 ICLK	
0008 9038h	S12AD	A/D data register 12	ADDR12	16	16	2, 3 PCLKB	2 ICLK	
0008 903Ah	S12AD	A/D data register 13	ADDR13	16	16	2, 3 PCLKB	2 ICLK	
0008 903Ch	S12AD	A/D data register 14	ADDR14	16	16	2, 3 PCLKB	2 ICLK	
0008 903Eh	S12AD	A/D data register 15	ADDR15	16	16	2, 3 PCLKB	2 ICLK	
0008 9040h	S12AD	A/D data register 16	ADDR16	16	16	2, 3 PCLKB	2 ICLK	
0008 9042h	S12AD	A/D data register 17	ADDR17	16	16	2, 3 PCLKB	2 ICLK	
0008 9044h	S12AD	A/D data register 18	ADDR18	16	16	2, 3 PCLKB	2 ICLK	
0008 9046h	S12AD	A/D data register 19	ADDR19	16	16	2, 3 PCLKB	2 ICLK	
0008 9048h	S12AD	A/D data register 20	ADDR20	16	16	2, 3 PCLKB	2 ICLK	
0008 9060h	S12AD	A/D sampling state register01	ADSSTR01	16	16	2, 3 PCLKB	2 ICLK	
0008 9070h	S12AD	A/D sampling state register 23	ADSSTR23	16	16	2, 3 PCLKB	2 ICLK	
0008 9800h	AD	A/D data register A	ADDRA	16	16	2, 3 PCLKB	2 ICLK	ADb
0008 9802h	AD	A/D data register B	ADDRB	16	16	2, 3 PCLKB	2 ICLK	
0008 9804h	AD	A/D data register C	ADDRC	16	16	2, 3 PCLKB	2 ICLK	
0008 9806h	AD	A/D data register D	ADDRD	16	16	2, 3 PCLKB	2 ICLK	
0008 9808h	AD	A/D data register E	ADDRE	16	16	2, 3 PCLKB	2 ICLK	
0008 980Ah	AD	A/D data register F	ADDRF	16	16	2, 3 PCLKB	2 ICLK	
0008 980Ch	AD	A/D data register G	ADDRG	16	16	2, 3 PCLKB	2 ICLK	
0008 980Eh	AD	A/D data register H	ADDRH	16	16	2, 3 PCLKB	2 ICLK	
0008 9810h	AD	A/D control/status register	ADCSR	8	8	2, 3 PCLKB	2 ICLK	
0008 9811h	AD	A/D control register	ADCR	8	8	2, 3 PCLKB	2 ICLK	
0008 9812h	AD	A/D control register 2	ADCR2	8	8	2, 3 PCLKB	2 ICLK	
0008 9813h	AD	A/D sampling state register	ADSSTR	8	8	2, 3 PCLKB	2 ICLK	
0008 981Fh	AD	A/D self-diagnostic register	ADDIAGR	8	8	2, 3 PCLKB	2 ICLK	
0008 A000h	SCI0	Serial mode register	SMR	8	8	2, 3 PCLKB	2 ICLK	SCIc, SCId
0008 A001h	SCI0	Bit rate register	BRR	8	8	2, 3 PCLKB	2 ICLK	
0008 A002h	SCI0	Serial control register	SCR	8	8	2, 3 PCLKB	2 ICLK	
0008 A003h	SCI0	Transmit data register	TDR	8	8	2, 3 PCLKB	2 ICLK	
0008 A004h	SCI0	Serial status register	SSR	8	8	2, 3 PCLKB	2 ICLK	
0008 A005h	SCI0	Receive data register	RDR	8	8	2, 3 PCLKB	2 ICLK	
0008 A006h	SCI0	Smart card mode register	SCMR	8	8	2, 3 PCLKB	2 ICLK	
0008 A007h	SCI0	Serial extended mode register	SEMR	8	8	2, 3 PCLKB	2 ICLK	
0008 A008h	SCI0	Noise filter setting register	SNFR	8	8	2, 3 PCLKB	2 ICLK	
0008 A009h	SCI0	I^{2}C mode register 1	SIMR1	8	8	2, 3 PCLKB	2 ICLK	
0008 A00Ah	SCI0	I^{2}C mode register 2	SIMR2	8	8	2, 3 PCLKB	2 ICLK	
0008 A00Bh	SCI0	I^{2}C mode register 3	SIMR3	8	8	2, 3 PCLKB	2 ICLK	
0008 A00Ch	SCI0	I^{2}C status register	SISR	8	8	2, 3 PCLKB	2 ICLK	
0008 A00Dh	SCI0	SPI mode register	SPMR	8	8	2, 3 PCLKB	2 ICLK	
0008 A020h	SCI1	Serial mode register	SMR	8	8	2, 3 PCLKB	2 ICLK	
0008 A021h	SCI1	Bit rate register	BRR	8	8	2, 3 PCLKB	2 ICLK	
0008 A022h	SCI1	Serial control register	SCR	8	8	2, 3 PCLKB	2 ICLK	
0008 A023h	SCI1	Transmit data register	TDR	8	8	2, 3 PCLKB	2 ICLK	
0008 A024h	SCI1	Serial status register	SSR	8	8	2, 3 PCLKB	2 ICLK	
0008 A025h	SCI1	Receive data register	RDR	8	8	2, 3 PCLKB	2 ICLK	
0008 A026h	SCI1	Smart card mode register	SCMR	8	8	2, 3 PCLKB	2 ICLK	
0008 A027h	SCI1	Serial extended mode register	SEMR	8	8	2, 3 PCLKB	2 ICLK	
0008 A028h	SCI1	Noise filter setting register	SNFR	8	8	2, 3 PCLKB	2 ICLK	
0008 A029h	SCI1	I^{2}C mode register 1	SIMR1	8	8	2, 3 PCLKB	2 ICLK	
0008 A02Ah	SCI1	I^{2}C mode register 2	SIMR2	8	8	2, 3 PCLKB	2 ICLK	

Table 4.1 List of I/O Registers (Address Order) (38/50)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States		Related Function
						ICLK≥PCLK	ICLK<PCLK	
000A 0000h	USB0	System configuration control register	SYSCFG	16	16	3 to 4 PCLKB	2, 3 ICLK	USBa
000A 0004h	USB0	System configuration status register 0	SYSSTS0	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB)*6	
000A 0008h	USB0	Device state control register 0	DVSTCTR0	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB)*6	
000A 0014h	USB0	CFIFO port register	CFIFO	16	8, 16	3 to 4 PCLKB	2, 3 ICLK	
000A 0018h	USB0	D0FIFO port register	D0FIFO	16	8, 16	3 to 4 PCLKB	2, 3 ICLK	
000A 001Ch	USB0	D1FIFO port register	D1FIFO	16	8, 16	3 to 4 PCLKB	2, 3 ICLK	
000A 0020h	USB0	CFIFO port select register	CFIFOSEL	16	16	3 to 4 PCLKB	2, 3 ICLK	
000A 0022h	USB0	CFIFO port control register	CFIFOCTR	16	16	3 to 4 PCLKB	2, 3 ICLK	
000A 0028h	USB0	D0FIFO port select register	D0FIFOSEL	16	16	3 to 4 PCLKB	2, 3 ICLK	
000A 002Ah	USB0	D0FIFO port control register	D0FIFOCTR	16	16	3 to 4 PCLKB	2, 3 ICLK	
000A 002Ch	USB0	D1FIFO port select register	D1FIFOSEL	16	16	3 to 4 PCLKB	2, 3 ICLK	
000A 002Eh	USB0	D1FIFO port control register	D1FIFOCTR	16	16	3 to 4 PCLKB	2, 3 ICLK	
000A 0030h	USB0	Interrupt enable register 0	INTENB0	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB)*6	
000A 0032h	USB0	Interrupt enable register 1	INTENB1	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB)*6	
000A 0036h	USB0	BRDY interrupt enable register	BRDYENB	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB)*6	
000A 0038h	USB0	NRDY interrupt enable register	NRDYENB	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB)*6	

Table 5.4 DC Characteristics (3) (for D and G Versions (-40 ≤ Ta ≤ +85°C))

Conditions: VCC = AVCC0 = VREFH = VCC_USB = V_{BATT} = 2.7 to 3.6 V, VREFH0 = 2.7 V to AVCC0,
VSS = AVSS0 = VREFL/VREFL0 = VSS_USB = 0 V, $T_a = T_{opr}$

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Supply current*1	High-speed operating mode	Max.*2		I_{CC}*3	—	—	100	mA	ICLK = 100 MHz PCLKA = 100MHz PCLKB = 50 MHz FCLK = 50 MHz BCLK = 100MHz
		Normal *4	Peripheral function: clock signal supplied*4		—	52	—		
			Peripheral function: clock signal stopped*4		—	40	—		
		Sleep mode			—	25	65		
		All-module-clock-stop mode (reference value)			—	20	38		
		Increased by BGO operation*5			—	15	—		
	Low-speed operating mode 1*6				—	4	—		ICLK = 1 MHz
	Low-speed operating mode 2				—	1	—		ICLK = 32.768 kHz
	Software standby mode				—	0.2	6		
	Deep software standby mode	Power supplied to RAM and USB resume detecting unit			—	22	200	µA	
		Power not supplied to RAM and USB resume detecting unit	Power-on reset circuit and low-power consumption function disabled		—	21	60		
			Power-on reset circuit and low-power		—	6.2	28		
	Increase when the RTC is operating		When a crystal oscillator for low clock loads is in use		—	1.0	—		
			When a crystal oscillator for standard clock loads is in use		—	3.0	—		
	RTC operating while VCC is off (with the battery backup function, only the RTC and sub-clock oscillator operate)		When a crystal oscillator for low clock loads is in use		—	0.9	—		V_{BATT} = 2.0 V, VCC = 0V
					—	1.6	—		V_{BATT} = 3.3 V, VCC = 0V
			When a crystal oscillator for standard clock loads is in use		—	1.7	—		V_{BATT} = 2.0 V(for products with 100 pins or more), VBATT = 2.3 V (for the 64-pin product), VCC = 0V
					—	3.3	—		V_{BATT} = 3.3 V, VCC = 0V
Analog power supply current*7	During 12-bit A/D conversion (including temperature sensor)			I_{AVCC0}	—	2.3	3.2	mA	
	During 10-bit A/D conversion			I_{VREFH}*9	—	1.0	1.65	mA	
	During D/A conversion (per unit)				—	0.7	1.0	mA	
	Waiting for A/D, D/A conversion (all units)*10			—	—	25	35	µA	
	A/D, D/A converter in standby mode (all units)*10				—	0.1	4.0	µA	
Reference power supply current	During 12-bit A/D conversion			I_{VREFH0}	—	0.6	0.7	mA	
	Waiting for 12-bit A/D conversion (per unit)				—	0.5	0.6	mA	
	12-bit A/D converter in standby mode (per unit)				—	0.1	2.0	µA	

Note 1. This is the time until the clock is used after setting P36 and P37 as inputs, and then clearing the main clock oscillator stop bit (MOSCCR.MOSTP) to 0 (selecting operation).

Note 2. This is the time until the frequency of oscillation by the HOCO (fHOCO) reaches the range for guaranteed operation after release from the reset state.

Note 3. When using a main clock, ask the manufacturer of the oscillator to evaluate its oscillation. Refer to the results of evaluation provided by the manufacturer for the oscillation stabilization time.

Note 4. The number of cycles n selected by the value of the MOSCWTCR.MSTS[4:0] bits determines the main-clock oscillation stabilization waiting time in accord with the formula below.

$$t_{MAINOSCWT} = t_{MAINOSC} + \frac{n + 16384}{f_{MAIN}}$$

Note 5. The number of cycles n selected by the value of the PLLWTCR.PSTS[4:0] bits determines the PLL-clock oscillation stabilization waiting time in accord with the formula below.

$$t_{PLLWT1} = t_{PLL1} + \frac{n + 131072}{f_{PLL}}$$

$$t_{PLLWT2} = t_{PLL2} + \frac{n + 131072}{f_{PLL}} = t_{MAINOSC} + t_{PLL1} + \frac{n + 131072}{f_{PLL}}$$

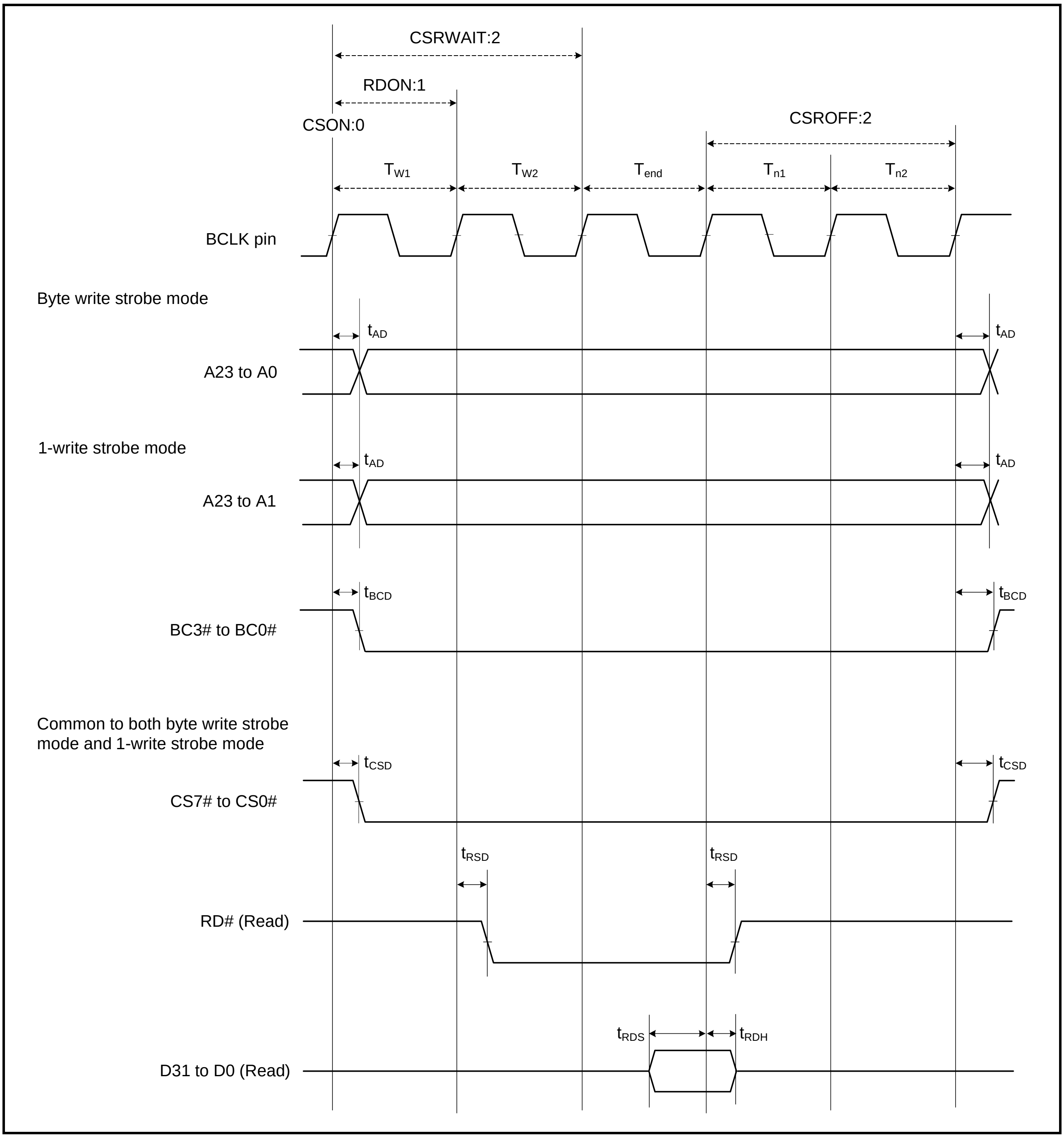


Figure 5.19 External Bus Timing/Normal Read Cycle (Bus Clock Synchronized)

Table 5.25 Timing of On-Chip Peripheral Modules (7)

Conditions: VCC = AVCC0 = VREFH = VCC_USB = 2.7 to 3.6 V, VREFH0 = 2.7 V to AVCC0
VSS = AVSS0 = VREFL/VREFL0 = VSS_USB = 0 V
ICLK = 12.5 to 100 MHz, $T_a = T_{opr}$
High drive output is selected by the drive capacity control register.

Item		Symbol	Min.	Max.	Unit	Test Conditions
ETHERC(RMII)	REF50CK cycle time	T_{ck}	20	—	ns	Figure 5.48 to Figure 5.51
	REF50CK frequency Typ. 50 MHz	—	—	50 + 100ppm	MHz	
	REF50CK duty	—	35	65	%	
	REF50CK rise/fall time	$T_{ckr/ckf}$	0.5	3.5	ns	
	RMII_xxxx*1 output delay time	T_{co}	2.5	15.0	ns	
	RMII_xxxx*2 setup time	T_{su}	3	—	ns	
	RMII_xxxx*2 hold time	T_{hd}	1	—	ns	
	RMII_xxxx*1, *2 rise/fall time	Tr/Tf	0.5	6	ns	
	ET_WOL output delay time	t_{WOLd}	1	23.5	ns	Figure 5.52
ETHERC(MII)	ET_TX_CLK cycle time	t_{Tcyc}	40	—	ns	—
	ET_TX_EN output delay time	t_{TENd}	1	20	ns	Figure 5.53
	ET_ETXD0 to ET_ETXD3 output delay time	t_{MTDd}	1	20	ns	
	ET_CRS setup time	t_{CRSs}	10	—	ns	
	ET_CRS hold time	t_{CRSh}	10	—	ns	
	ET_COL setup time	t_{COLs}	10	—	ns	Figure 5.54
	ET_COL hold time	t_{COLh}	10	—	ns	
	ET_RX_CLK cycle time	t_{TRcyc}	40	—	ns	—
	ET_RX_DV setup time	t_{RDVs}	10		ns	Figure 5.55
	ET_RX_DV hold time	t_{RDVh}	10	—	ns	
	ET_ERXD0 to ET_ERXD3 setup time	t_{MRDs}	10	—	ns	
	ET_ERXD0 to ET_ERXD3 hold time	t_{MRDh}	10	—	ns	
	ET_RX_ER setup time	t_{RERs}	10	—	ns	Figure 5.56
	ET_RX_ER hold time	t_{RESh}	10	—	ns	
	ET_WOL output delay time	t_{WOLd}	1	23.5	ns	Figure 5.57

Note 1. RMII_TXD_EN, RMII_TXD1, RMII_TXD0.
Note 2. RMII_CRS_DV, RMII_RXD1, RMII_RXD0, RMII_RX_ER

Table 5.26 Timing of On-Chip Peripheral Modules (8)

Conditions: VCC = AVCC0 = VREFH = VCC_USB = 2.7 to 3.6V, VREFH0 = 2.7V to AVCC0,
VSS = AVSS0 = VREFL/VREFL0 = VSS_USB = 0V, PIXCLK = 27MHz, $T_a = T_{opr}$

Item		Symbol	min	typ	max	Unit	Test Conditions
PDC	VSYNC/HSYNC input setup time	$t_{SYNCSETUP}$	10	—	—	ns	Figure 5.58
	VSYNC/HSYNC input hold time	$t_{SYNCHOLD}$	5	—	—	ns	
	PIXD input setup time	$t_{DATASETUP}$	10	—	—	ns	
	PIXD input hold time	$t_{DATAHOLD}$	5	—	—	ns	
	PIXCLK input cycle time	t_{PIXcyc}	37	—	1000	ns	Figure 5.59
	PIXCLK input pulse width high level	t_{PIXH}	10	—	—	ns	
	PIXCLK input pulse width low level	t_{PIXL}	10	—	—	ns	
	PCKO pin output cycle time	t_{PCKcyc}	40	—	1000	ns	Figure 5.60
	PCKO pin output high level pulse width	t_{PCKH}	13	—	—	ns	
	PCKO pin output low level pulse width	t_{PCKL}	13	—	—	ns	
	PCKO pin output rising time	t_{PCKr}	—	—	5	ns	
	PCKO pin output falling time	t_{PCKf}	—	—	5	ns	

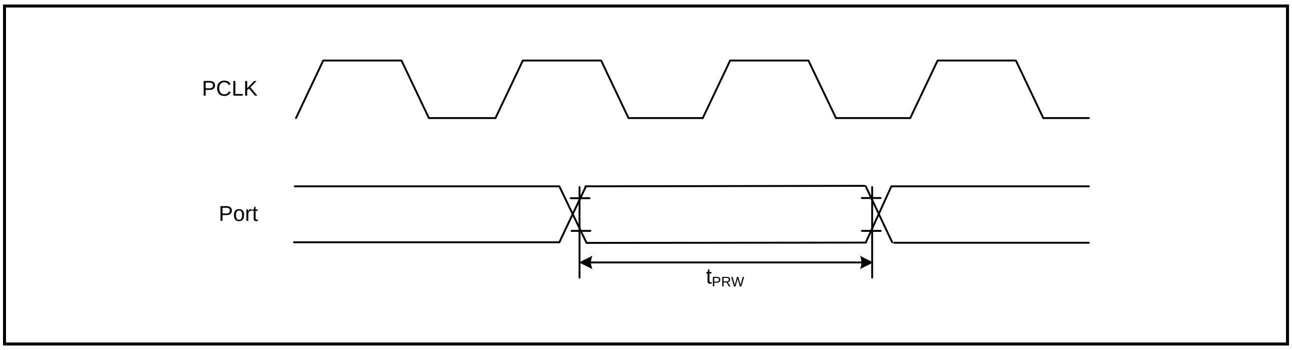


Figure 5.34 I/O Port Input Timing

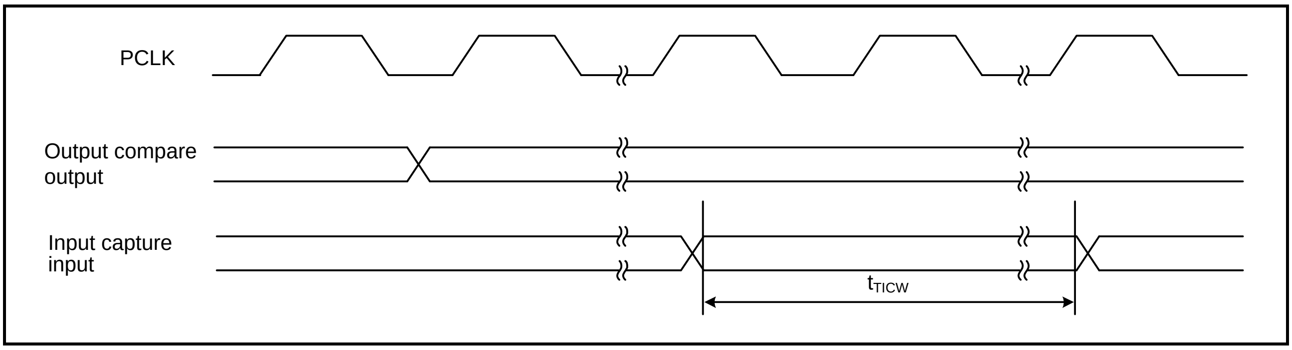


Figure 5.35 MTU Input/Output Timing

5.5 A/D Conversion Characteristics

Table 5.28 10-Bit A/D Conversion Characteristics

Conditions: VCC = AVCC0 = VREFH = VCC_USB = 2.7 to 3.6 V, VREFH0 = 2.7 V to AVCC0
VSS = AVSS0 = VREFL/VREFL0 = VSS_USB = 0 V
PCLK = 8 to 50 MHz
$T_a = T_{opr}$

Item			Min.	Typ.	Max.	Unit	Test Conditions
Resolution			—	—	10	Bit	
Conversion time*1 (Operation at PCLK = 50 MHz)	With 0.1-µF external capacitor	When the capacitor is charged enough*2	3.0 (2.5)*3	—	—	µs	Sampling in 125 states
	Without 0.1-µF external capacitor	Permissible signal source impedance (max.) = 1.0 kΩ, VCC ≥ 3.0 V	1.5 (1.0)*3	—	—		Sampling in 50 states
		Permissible signal source impedance (max.) = 1.0 kΩ, VCC ≥ 2.7 V	3.5 (3.0)*3	—	—		Sampling in 150 states
		Permissible signal source impedance (max.) = 5.0 kΩ, VCC ≥ 3.0 V	2.0 (1.5)*3	—	—		Sampling in 75 states
		Permissible signal source impedance (max.) = 5.0 kΩ, VCC ≥ 2.7 V	4.0 (3.5)*3	—	—		Sampling in 175 states
Analog input capacitance			—	—	6.0	pF	
Offset error			—	±1.5	±3.0	LSB	
Full-scale error			—	±1.5	±3.0	LSB	
Quantization error			—	±0.5	—	LSB	
Absolute accuracy			—	±1.5	±3.0	LSB	
DNL differential nonlinearity error			—	±0.5	±1.0	LSB	
INL integral nonlinearity error			—	±1.5	±3.0	LSB	

Note: The above specification values apply when there is no access to the external bus during A/D conversion. If access proceeds during A/D conversion, values may not fall within the above ranges.
Note 1. The conversion time includes the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.
Note 2. The scanning is not supported.
Note 3. The value in parentheses indicates the sampling time.

Rev.	Date	Description	
		Page	Summary
1.70	Oct 08. 2013	80 to 127	Table 4.1 List of I/O Registers (Address Order), changed
		5. Electrical Characteristics	
		131, 132	Table 5.4 DC Characteristics (3), changed, Note. 9, Note. 10, added
		133	Table 5.6 Permissible Output Currents, changed
		139	Table 5.12 Clock Timing (Sub-Clock Related), Note 3, added
		167	Table 5.25 Timing of On-Chip Peripheral Modules (8), added
		175	Figure 5.58 PDC Timing, added
		175	Figure 5.59 PDC Input Clock Characteristic, added
		176	Figure 5.60 PDC Output Clock Characteristic, added
		178	Table 5.27 10-Bit A/D Conversion Characteristics, changed
		179	Table 5.28 12-Bit A/D Conversion Characteristics, changed
		185	Table 5.35 ROM (Flash Memory for Code Storage) Characteristics (1), added
		185	Table 5.36 ROM (Flash Memory for Code Storage) Characteristics (2), changed
		186	Table 5.37 E2 Flash Characteristics (1), added
		186	Table 5.38 E2 Flash Characteristics (2), changed
		Appendix 1.Package Dimensions	
		197	Figure H 64-pin TFLGA (PTLG0064JA-A), added

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   — The characteristics of an MPU or MCU in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.